

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	8.5mΩ@10V	65A
	11mΩ@4.5V	



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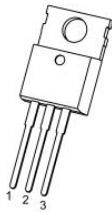
Feature

- Fast Switching
- Low Gate Charge and Rds on
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

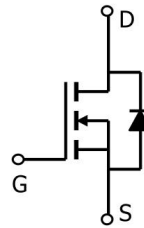
- Power switching application
- PWM Application
- DC-DC Converter

Package

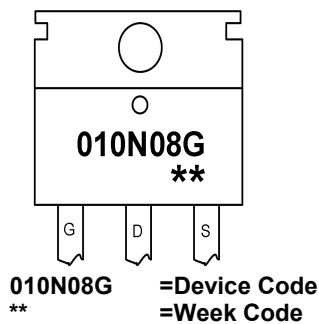


TO-220-3L-C(1:G 2:D 3:S)

Circuit diagram



Marking



Order Information

Device	Package	Unite/Tube
SP010N08GTQ	TO-220-3L	50

Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current (Tc=25°C)	I _D	65	A
Pulsed Drain Current ²	I _{DM}	260	A
Single Pulse Avalanche Energy ³	E _{AS}	156	mJ
Total Power Dissipation ⁴ (Tc=25°C)	P _D	90	W
Thermal Resistance Junction-Case ¹	R _{θJC}	1.38	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

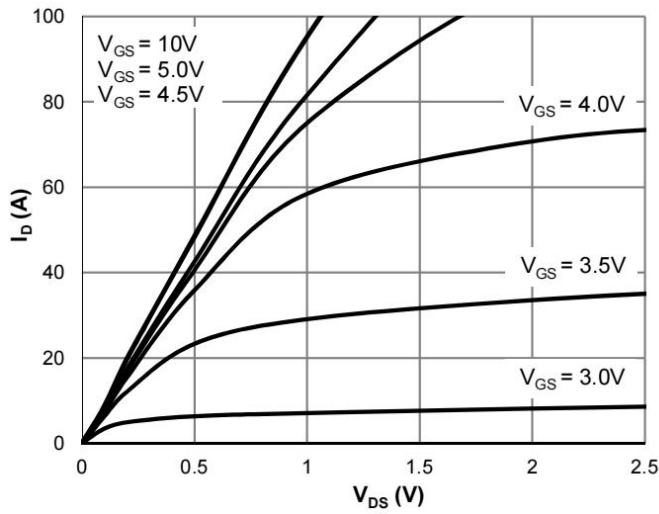
Electrical characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V, ID=250uA	100	---	---	V
Drain-Source Leakage Current	IDSS	VDS=80V, VGS=0V, TJ=25°C	---	---	1	uA
Gate-Source Leakage Current	IGSS	VGS=±20V, VDS=0V	---	---	±100	nA
Gate Threshold Voltage	VGS(th)	VGS=VDS, ID=250uA	1.2	1.9	2.5	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	VGS=10V, ID=20A	---	8.5	12	mΩ
		VGS=4.5V, ID=15A	---	11	15	
Dynamic Characteristics						
Input Capacitance	C _{iss}	VDS=50V, VGS=0V, f=1MHz	---	1635	---	pF
Output Capacitance	C _{oss}		---	339	---	
Reverse Transfer Capacitance	C _{rss}		---	22	---	
Switching Characteristics						
Total Gate Charge (4.5V)	Q _g	VDS=50V, VGS=10V, ID=20A	---	14	---	nC
Gate-Source Charge	Q _{gs}		---	5	---	
Gate-Drain Charge	Q _{gd}		---	7	---	
Turn-On Delay Time	T _{d(on)}	VDD=50V, VGS=10V, RL=2.5Ω, RG=6Ω	---	8	---	ns
Rise Time	T _r		---	16	---	
Turn-Off Delay Time	T _{d(off)}		---	31	---	
Fall Time	T _f		---	27	---	
Source-Drain Diode Characteristics						
Diode Forward Voltage ²	V _{SD}	VGS=0V, IS=1A, TJ=25°C	---	---	1.2	V

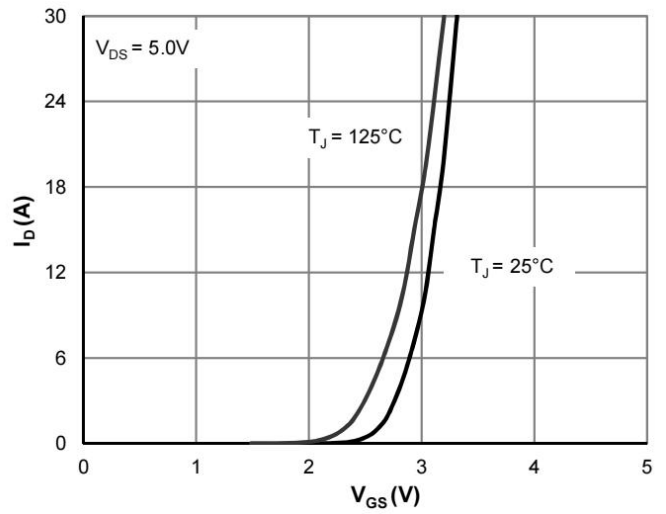
Note :

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- The EAS data shows Max. rating. The test condition is VDD=50V, VGS=10V, L=0.5mH, Rg=25Ω
- The power dissipation is limited by 150°C junction temperature

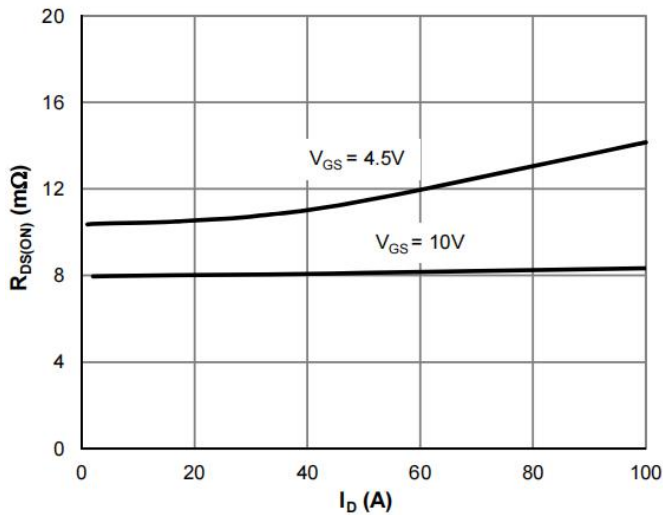
Typical Characteristics



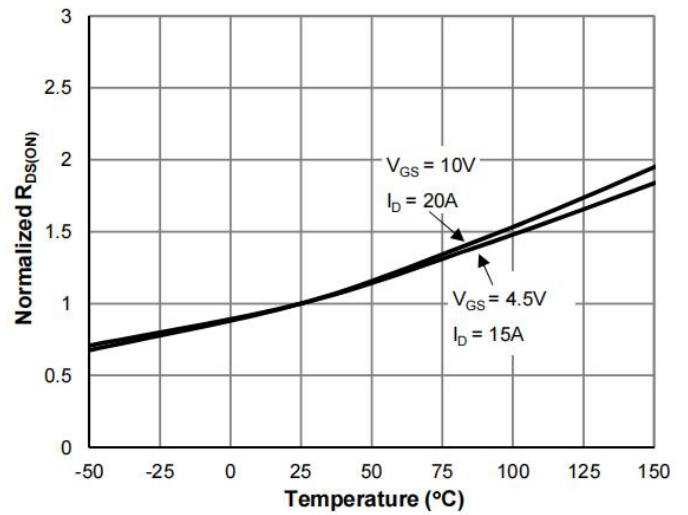
Typical Output Characteristics



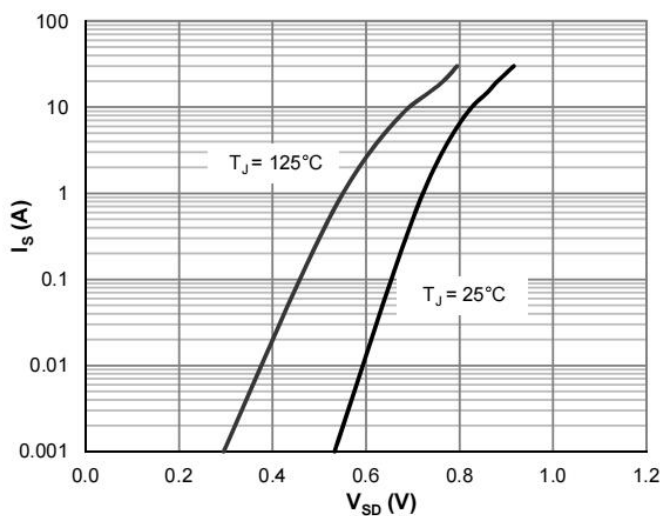
Transfer Characteristics



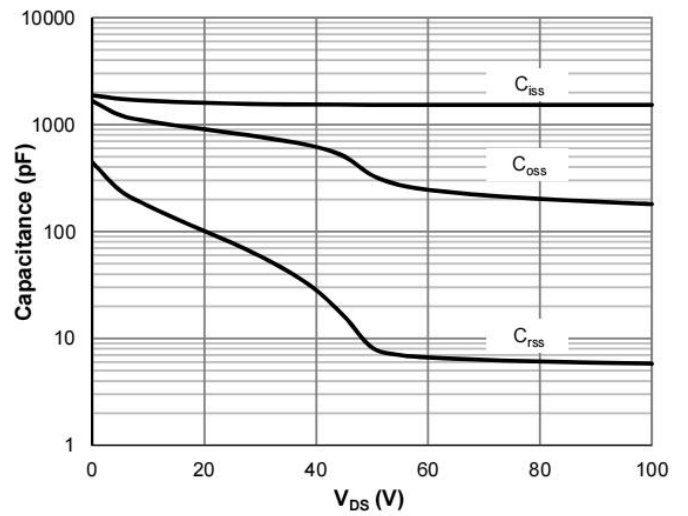
On-Resistance vs. Drain Current



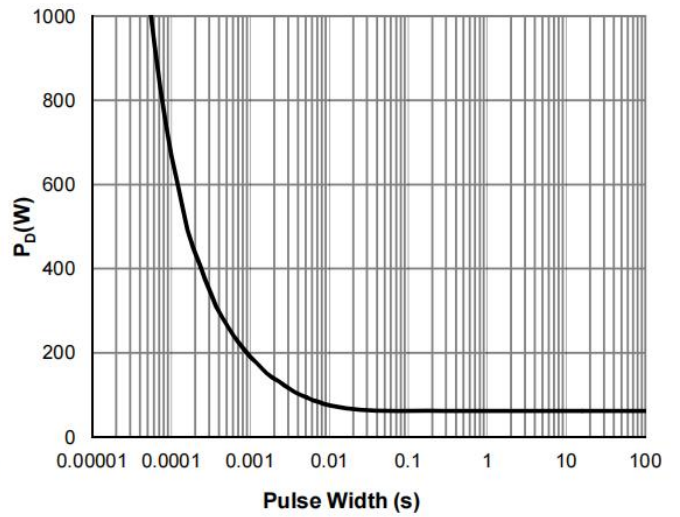
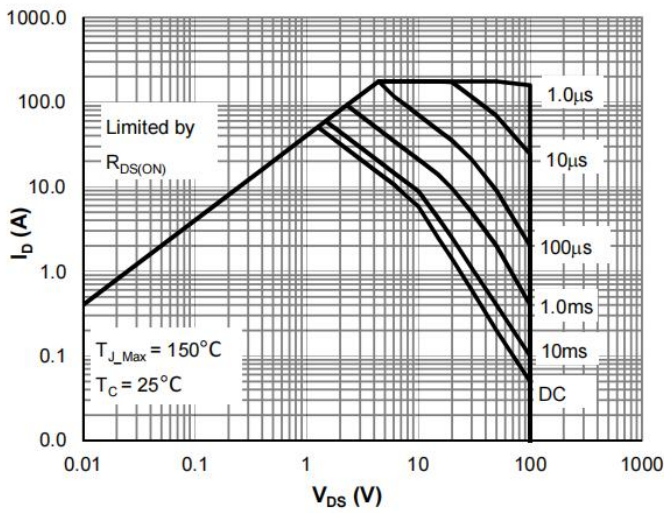
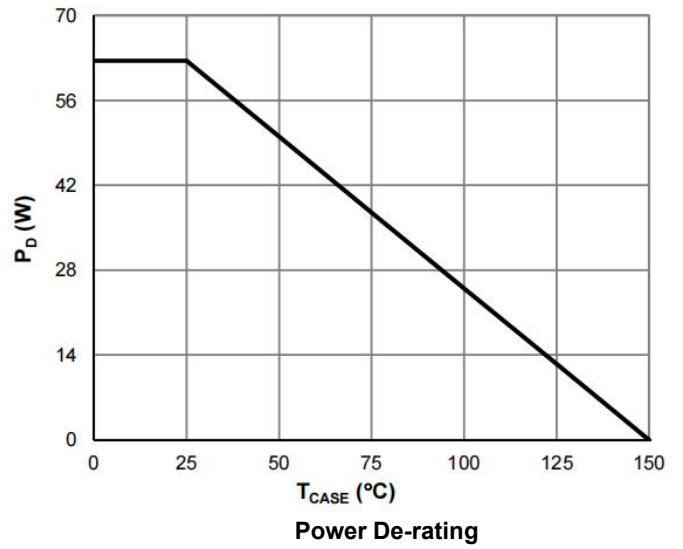
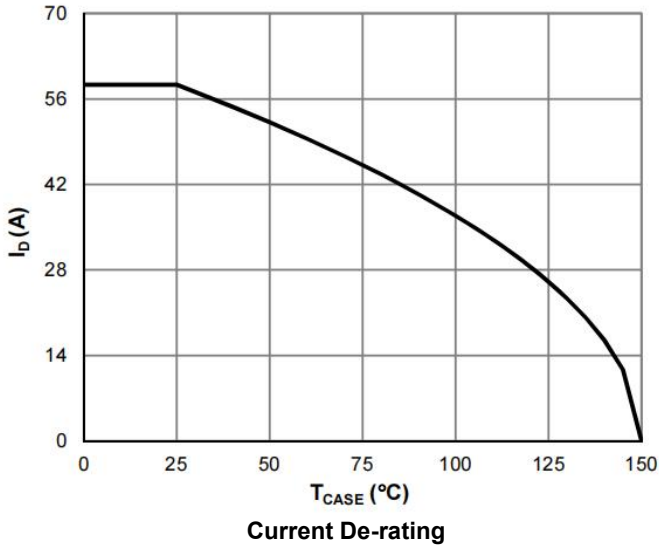
On-Resistance vs. Junction Temperature



Body-Diode Characteristics

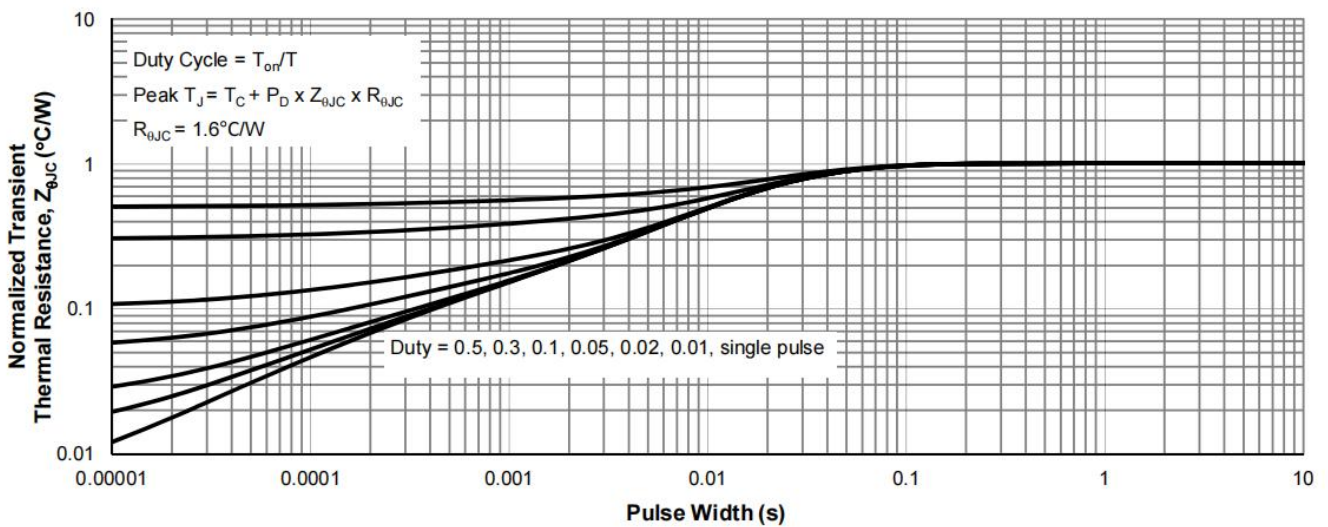


Capacitance Characteristics



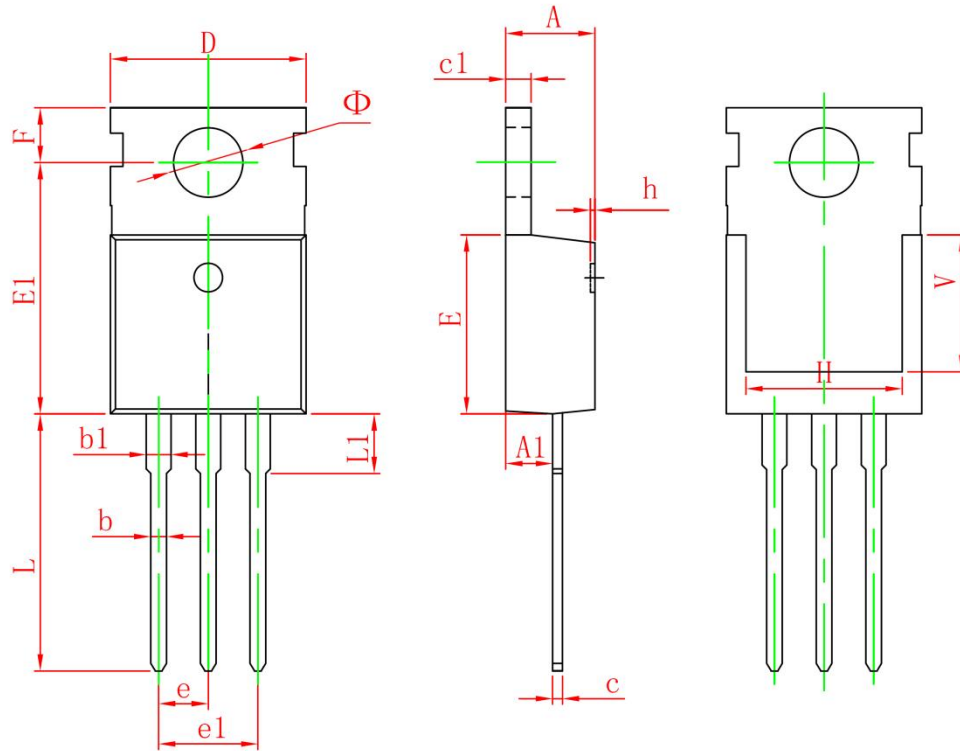
Maximum Safe Operating Area

Single Pulse Power Rating, Junction-to-Case



Normalized Maximum Transient Thermal Impedance

TO-220-3L-C Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	13.050	0.498	0.514
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150